

S-395 N2

Micronized Wax

Shamrock's product line of micronized waxes provide rub and abrasion resistance. Included in this line are products that provide gloss, matting, clarity, and controlled slip in a range of particle sizes.

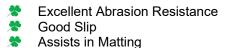
Product Description:

S-395-N2 is a synthetic wax with a DSC melt peak above 120°C, good crystallinity and high onset of melt.

Application:

S-395-N2 is recommended for liquid and paste inks. S-395-N2 is also recommended for use in many types of coating systems including solvent-based, water-based, UV, and powder coatings.S-395-N2 can be used for both pigmented and clear compositions. S-395-N2 is recommended at 2-3% of total formula weight for slip and abrasion resistance and 5-10% for matting.

Features and Benefits:



Typical Properties:

*	Specific Gravity:	0.95 g/cm ³
*	Particle Size Mean Value:	6 µm
*	99% of Particle Under:	13 µm
*	NPIRI Grind:	2.5 Max
*	Hegman Grind:	6.5 Min
	Melting Point:	248°F / 120°C

Regulatory Status

The components of this product are listed on multiple chemical inventories. For specific information on the applicable chemical inventories, please refer to the product SDS.

Safety, Shipping and Handling

For complete shipping, handling, health and safety information please contact your regional Customer Service Representative. Please contact them at your convenience for instructions and Material Safety Data Sheets, the contact information is located below.

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